

# INTERNATIONAL STANDARD

# NORME INTERNATIONALE



**Field device integration (FDI) –  
Part 4: FDI Packages**

**Intégration des appareils de terrain (FDI) –  
Partie 4: Paquetages FDI**



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IEC Central Office  
3, rue de Varembe  
CH-1211 Geneva 20  
Switzerland

Tel.: +41 22 919 02 11  
[info@iec.ch](mailto:info@iec.ch)  
[www.iec.ch](http://www.iec.ch)

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# INTERNATIONAL STANDARD

## NORME INTERNATIONALE



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Part 4: FDI Packages**

**Intégration des appareils de terrain (FDI) –  
Partie 4: Paquetages FDI**

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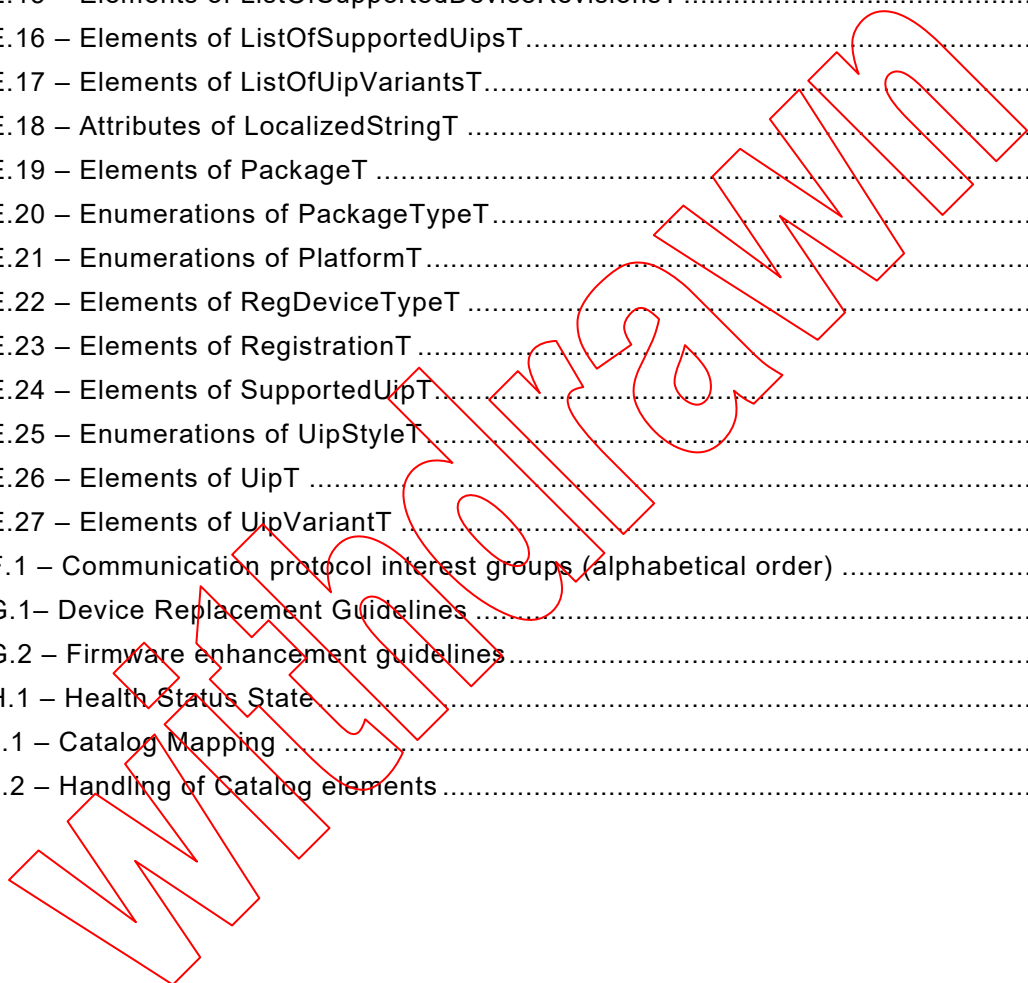
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## FIELD DEVICE INTEGRATION (FDI) –

## Part 4: FDI Packages

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International Standard IEC 62769-4 has been prepared by subcommittee 65E: Devices and integration in enterprise systems, of IEC technical committee 65: Industrial-process measurement, control and automation.

This second edition cancels and replaces the first edition published in 2015. This edition constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

- a) support for Package Developers to build EDDs targeted for today's EDD bases system under a single development tool;
- b) digital signature now includes trusted timestamping for long-term validation of FDI Package;
- c) time stamp for device package signature.

The text of this International Standard is based on the following documents:

FDIS	Report on voting
65E/761/FDIS	65E/771/RVD

Full information on the voting for the approval of this International Standard can be found in the report on voting indicated in the above table.

This document has been drafted in accordance with the ISO/IEC Directives, Part 2.

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## INTRODUCTION

The IEC 62769 series has the general title *Field Device Integration (FDI)* and the following parts:

- Part 1: Overview
- Part 2: FDI Client
- Part 3: FDI Server
- Part 4: FDI Packages
- Part 5: FDI Information Model
- Part 6: FDI Technology Mapping
- Part 7: FDI Communication Devices
- Part 100: Profiles – Generic Protocol Extensions
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- Part 101-2: Profiles – Foundation Fieldbus HSE
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